



# Low Residue No Clean Flux For Lead Free Soldering

### Description:

AF 4818-PbF is low residues no clean flux containing modified rosin in a specialty blend solvent vehicle containing controlled amount of synergistic organic activating agents.

The residues left on the board is minimal, non hygroscopic and possesses high surface insulation resistance thus making AF 4818-PbF particularly suitable for no clean application.

AF 4818-PbF is suitable for use in manufacturing of high reliability products like telecommunication equipments, computers etc.



### Key Features and Benefits:

- Residue Free

After soldering, the joints are shiny, board surface tack free hence pose no problem to pin testing.

- No More Bridging

AF 4818-PbF has “tack” to keep the activators at the soldering site hence not easily washed off by the high pressure solder waves. This property coupled with the thermally stable activator system makes AF 4818-PbF particularly effective against bridging and skipped solder.

- Inhibits Solder Balling

AF 4818-PbF contains a unique additive that inhibits the formation of solder ball. AF 4818-PbF is more effective preventing solder ball formation than any competitive product.

### Specifications:

Appearance	Clear Amber Liquid
Specific Gravity @ °C	0.798
Solid Content Wt %	5.0 %
Halide Content Wt %	0.00 %
Acid Number mg KOH/mg	19.0
Flash Point °F	62.0
Thinner	T 1000
Flux Control (Specific Gravity)	Between 0.793 & 0.803

### Chemical and Electrical Properties:

Silver Chromate Paper Test	Pass
Copper Corrosion Test	Pass
Corrosion Mirror Test	Pass
Surface Insulation Test 7 days @ 85°C/85% RH	>1 X 10e08

### Standard Packaging:

Standard Packaging for AF 4818-PbF is 20 liters net per drum.

### Handling Precautions:

The labels on containers of Interflux® materials contain current information on the hazards associated with each particular product. Before using this or any other Interflux® product, refer to the Material Safety Data Sheet (MSDS) and label for safe use and handling.

